



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
60V	2Ω @ V _{GS} = 5V	380mA
007	2.5Ω @ $V_{GS} = 2.5V$	340mA

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

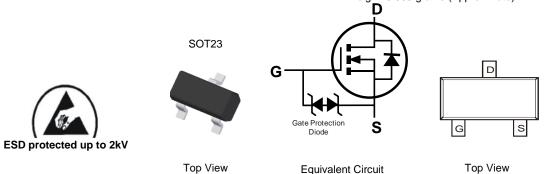
- Motor Control
- Power Management Functions
- Backlighting

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Up To 2kV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.008 grams (Approximate)



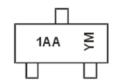
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN61D9U-7	SOT23	3000/Tape & Reel
DMN61D9U-13	SOT23	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



1AA = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: C = 2015) M = Month (ex: 9 = September)

Date Code Kev

Year	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025
Code	В	С	D	E	F	G	Н	I	J	K	L	M
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		V_{DSS}	60	V	
Gate-Source Voltage		V_{GSS}	±20	V	
Steady $T_A = +25$ State $T_A = +70$			I _D	380 300	mA
Continuous Drain Current (Note 6) V _{GS} = 5.0V	t<5s	I _D	430 340	mA	
Maximum Continuous Body Diode Forward Current	(Note 6)	Is	0.4	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) (Note 6)			I _{DM}	1.2	А

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

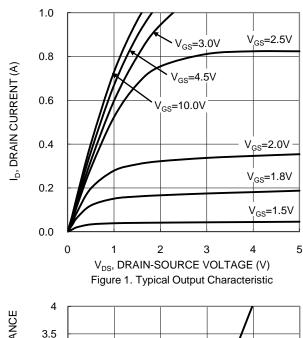
Characteristic		Symbol	Value	Unit	
Total Power Dissipation (Note 5)		P_{D}	370	mW	
Steady State		Б	351	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<5s	$R_{\theta JA}$	292	*C/vv	
Total Power Dissipation (Note 6)		P_{D}	540	mW	
Thermal Resistance, Junction to Ambient (Note 6)	Б	221	°C/W		
Thermal Resistance, Junction to Ambient (Note 6)	t<5s	$R_{\theta JA}$	197	C/VV	
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}		_	1.0	μΑ	$V_{DS} = 60V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.5	_	1.0	V	$V_{DS} = 10V, I_D = 250\mu A$
			1.2	2.0		$V_{GS} = 5.0V, I_D = 0.05A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	1.6	2.5	Ω	$V_{GS} = 2.5V, I_D = 0.05A$
			2.5	3.5		$V_{GS} = 1.8V, I_D = 0.05A$
Forward Transconductance	Y _{fs}	200	_	_	mS	$V_{DS} = 10V, I_D = 0.2A$
Diode Forward Voltage	V_{SD}	_	0.75	1.4	V	V _{GS} = 0V, I _S = 115mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}		28.5	_	pF	V 00V V 0V
Output Capacitance	Coss	_	3.9	_	pF	$V_{DS} = 30V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	2.5	_	pF	1 = 1.0W112
Gate Resistance	Rq	_	65	_	Ω	$f = 1MHz$, $V_{GS} = 0V$, $V_{DS} = 0V$
Total Gate Charge	Qg	_	0.4	_	nC	451/1/ 401/
Gate-Source Charge	Q _{qs}	_	0.1	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Drain Charge	Q _{qd}	_	0.1	_	nC	I _D = 250mA
Turn-On Delay Time	t _{D(ON)}	_	2.1	_	ns	
Turn-On Rise Time	t _R	_	1.8	_	ns	$V_{DD} = 30V, V_{GS} = 10V,$
Turn-Off Delay Time	t _{D(OFF)}		14.4	_	ns	$R_G = 25\Omega$, $I_D = 200mA$
Turn-Off Fall Time	t _F	_	8.4	_	ns	

- Device mounted on FR-4 PCB, with minimum recommended pad layout.
 Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
 Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.





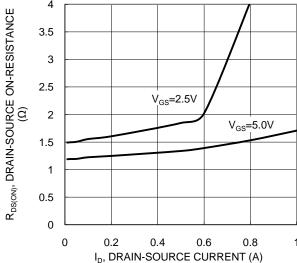
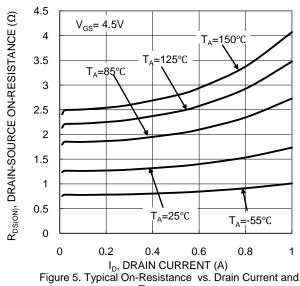
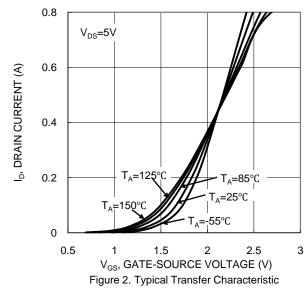
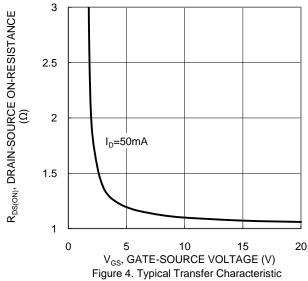


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage



Temperature





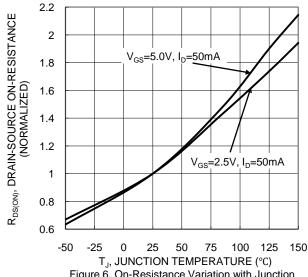


Figure 6. On-Resistance Variation with Junction Temperature



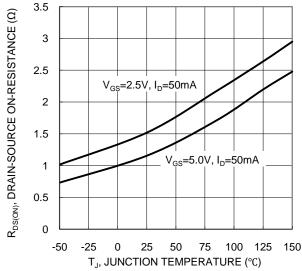
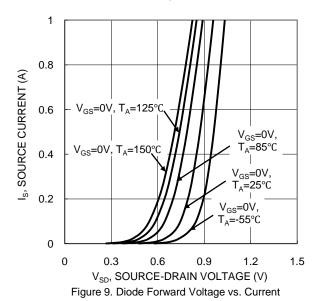


Figure 7. On-Resistance Variation with Junction Temperature



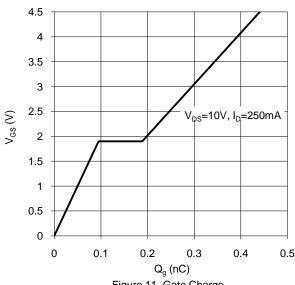


Figure 11. Gate Charge

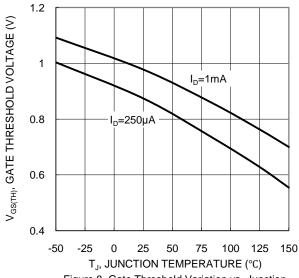
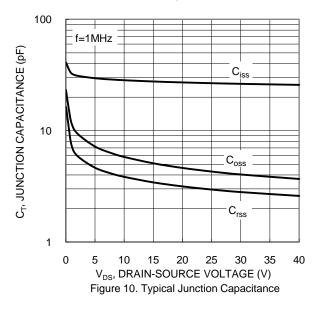
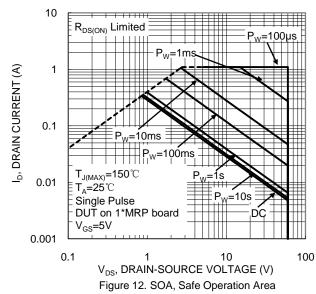
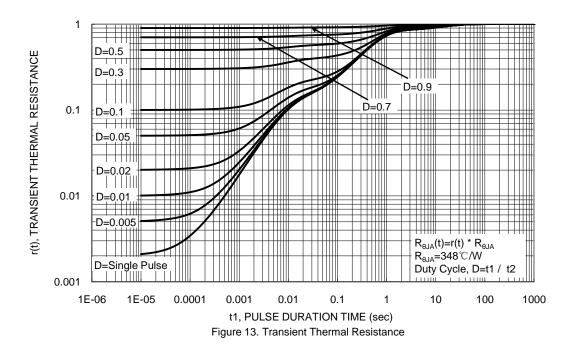


Figure 8. Gate Threshold Variation vs. Junction Temperature



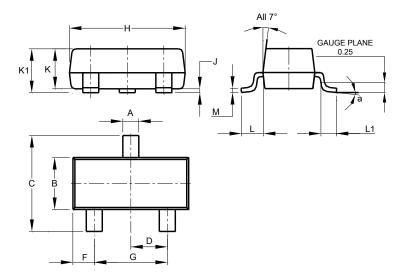






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

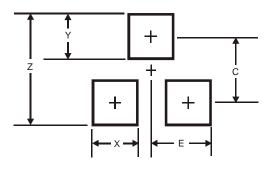


SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
M	0.085	0.150	0.110				
а	a 8°						
All Dimensions in mm							



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35

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